

# ECE321 Electronics I: Lecture 4

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## Chapter 3 Solid-State Diodes and Diode Circuits Sections 3.1-3.5

### Microelectronic Circuit Design

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## Lecture Goals

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- Understand diode structure and basic layout
- Develop electrostatics of the  $pn$  junction
- Define regions of operation of the diode (forward bias, reverse bias, and reverse breakdown)

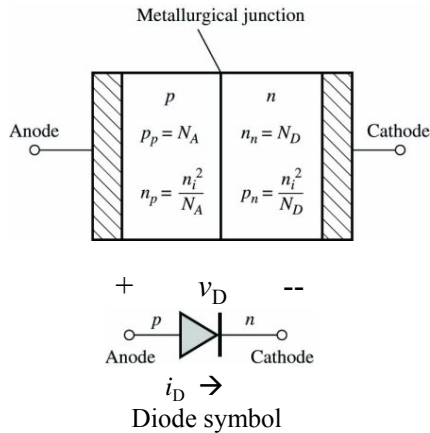
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# Diode Introduction



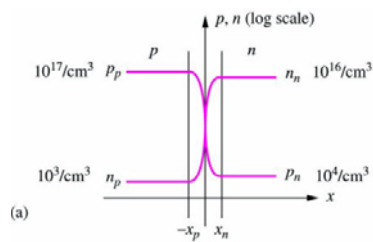
- A diode is formed by joining an  $n$ -type semiconductor with a  $p$ -type semiconductor.
- A  **$pn$  junction** is the interface between  $n$  and  $p$  regions.
- e.g.  $N_D=10^{16}/\text{cm}^3$ ,  $N_A=10^{17}/\text{cm}^3$   
 $N$  side:  $n_n=N_D=10^{16}/\text{cm}^3$   
 $p_n=n_i^2/n_n=10^{20}/10^{16}=10^4/\text{cm}^3$   
 $P$  side:  $p_p=N_A=10^{17}/\text{cm}^3$   
 $n_p=n_i^2/p_p=10^{20}/10^{17}=10^3/\text{cm}^3$

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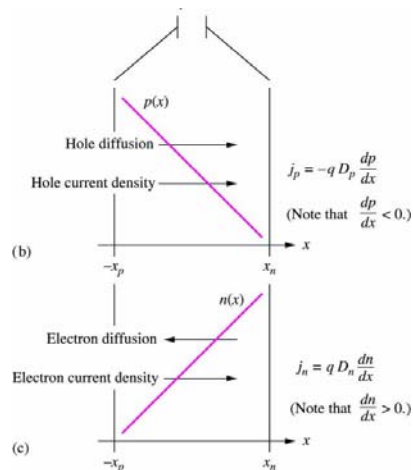
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# $pn$ Junction Electrostatics



Donor and acceptor concentration on either side of the junction. Concentration gradients give rise to diffusion currents.



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## Drift Currents

- Diffusion currents lead to localized charge density variations near the *pn* junction.
- Gauss' law predicts an electric field due to the charge distribution:

$$\nabla \cdot E = \frac{\rho_c}{\epsilon_s}$$

- Assuming constant permittivity,

$$E(x) = \frac{1}{\epsilon_s} \int \rho(x) dx$$

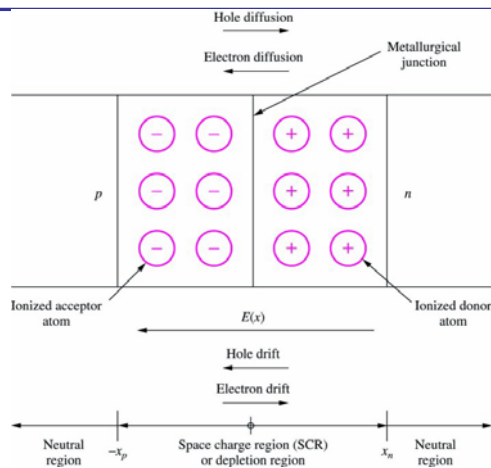
- Resulting electric field gives rise to a drift current. With no external circuit connections, drift and diffusion currents cancel. There is no actual current, since this would imply power dissipation, rather the electric field cancels the diffusion current 'tendency.'

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## Space-Charge Region (SCR) Formation at the *pn* Junction



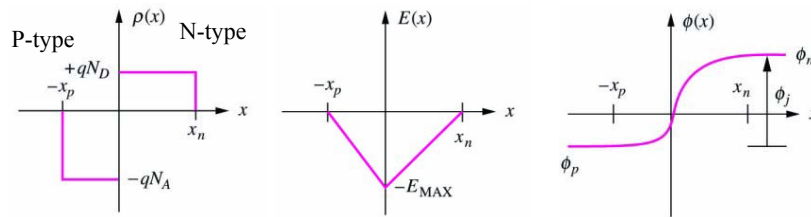
Electrons from N-type and holes from P-type migrate across the boundary by diffusion, and recombine, leaving immobile doping impurity ions (charges) to form the SCR (no mobile carriers.) The electric field in this "depletion region" inhibits further diffusion.

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## Potential Across the Junction



Charge Density

$$qN_A x_p = qN_D x_n$$

Electric Field

$$E(x) = \frac{1}{\epsilon_s} \int \rho(x) dx$$

Potential

$$\phi_j = - \int E(x) dx = V_T \ln \left( \frac{N_A N_D}{n_i^2} \right), \quad V_T = \frac{kT}{q}$$

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## Width of Depletion Region

Combining the previous expressions, we can form an expression for the width of the space-charge region, or depletion region. It is called the depletion region since the excess holes and electrons are depleted from the dopant atoms on either side of the junction.

$$w_{d0} = (x_n + x_p) = \sqrt{\frac{2\epsilon_s}{q} \left( \frac{1}{N_A} + \frac{1}{N_D} \right) \phi_j}$$

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## Junction Width and Potential

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N-type side:  $\rho_C = +qN_D$                       (P-type side:  $\rho_C = -qN_A$ )

$$\begin{aligned} d^2V/dx^2 &= -\rho_C/\epsilon_s \quad \text{so } E(x) = -dV/dx = \int(\rho_C/\epsilon_s)dx \\ &= (q/\epsilon_s)N_Dx + \text{const} \\ &= 0 \text{ at } x = x_n \text{ so const} = -(q/\epsilon_s)N_Dx_n \\ \text{and } E(x) &= -(q/\epsilon_s)N_D(x_n - x) \\ \text{and } E_{\max} &= -(q/\epsilon_s)N_Dx_n \text{ at } x = 0 \end{aligned}$$

$$\begin{aligned} \text{So } V(x) &= -\int E(x)dx = +(q/\epsilon_s)N_D(x_nx - x^2/2) + \text{const} \\ &= 0 \text{ at } x = 0, \text{ so const} = 0 \end{aligned}$$

$$\text{Hence } V(x_n) = \phi_n = (qN_D/2\epsilon_s)x_n^2 \text{ so } \phi_j = \phi_n + \phi_p = (q/2\epsilon_s)(x_n^2N_D + x_p^2N_A)$$

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## Junction Width (cont'd)

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From last slide:  $\phi_j = \phi_n + \phi_p = (q/2\epsilon_s)(x_n^2N_D + x_p^2N_A)$

Substitute for  $x_n$  from:  $N_Ax_p = N_Dx_n$

to get:  $\phi_j = (q/2\epsilon_s)([N_A^2x_p^2/N_D^2]N_D + x_p^2N_A)$

Rearrange, and hence:  $x_p^2 = (2\epsilon_s\phi_j/q)(N_A + N_A^2/N_D)$

$$x_p = (2\epsilon_s\phi_j/q)^{1/2}(N_A + N_D)^{-1/2}(N_D/N_A)^{1/2}$$

So  $W = x_p + x_n = (2\epsilon_s\phi_j/q)^{1/2}(N_A + N_D)^{-1/2} [(N_D/N_A)^{1/2} + (N_A/N_D)^{1/2}]$

$$= (2\epsilon_s\phi_j/q)^{1/2}(N_A + N_D)^{1/2} (N_DN_A)^{-1/2}$$

$$= (2\epsilon_s\phi_j/q)^{1/2}(1/N_A + 1/N_D)^{1/2}$$

Also  $E_{\max} = -(q/\epsilon_s)N_Ax_p$

$$= -(2q\phi_j/\epsilon_s)^{1/2}(N_A + N_D)^{-1/2}(N_DN_A)^{1/2} = -2\phi_j / W$$

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## Internal Diode Currents

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Mathematically, for a diode with no external connections, the total current expressions developed in Chapter 2 are equal to zero. The equations only dictate that the total currents are zero. However, as mentioned earlier, since there is no power dissipation, we must assume that the field and diffusion current tendencies cancel and the actual currents are zero.

$$j_n^T = q\mu_n nE + qD_n \frac{\partial n}{\partial x} = 0$$

$$j_p^T = q\mu_p pE - qD_p \frac{\partial p}{\partial x} = 0$$

When external bias voltage is applied to the diode, the above equations are no longer equal to zero.

## Junction Potential (cont'd)

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Considering total hole current:

$$j_p = q\mu_p pE - qD_p (dp/dx) = 0 \text{ at equilibrium}$$

So  $- \mu_p p (dV/dx) = D_p (dp/dx)$

$$- \mu_p / D_p dV = dp/p$$

and

$$- \frac{\mu_p}{D_p} \int_{-x_p}^{x_n} dV = \int_{p_p}^{p_n} \frac{dp}{p}$$

Einstein  $\rightarrow - (kT/q)\phi_j = \log_e p_n - \log_e p_p$

$$\phi_j = (q/kT) \log_e (p_p/p_n)$$

$$= (q/kT) \log_e (N_A N_D / n_i^2)$$

## Width of Depletion Region (Example)

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**Problem:** Find built-in potential and depletion-region width for given diode

**Given data:** On  $p$ -type side:  $N_A = 10^{17}/\text{cm}^3$  on  $n$ -type side:  $N_D = 10^{20}/\text{cm}^3$

**Assumptions:** Room-temperature operation with  $V_T = 0.025 \text{ V}$

**Analysis:**

$$\phi_j = V_T \ln \left( \frac{N_A N_D}{n_i^2} \right) = (0.025 \text{ V}) \left[ \ln \frac{(10^{17}/\text{cm}^3)(10^{20}/\text{cm}^3)}{(10^{20}/\text{cm}^6)} \right] = 0.979 \text{ V}$$

$$w_{d0} = \sqrt{\frac{2\epsilon_s}{q} \left( \frac{1}{N_A} + \frac{1}{N_D} \right) \phi_j} = 0.113 \mu\text{m}$$

## Diode Electric Field (Example)

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• **Problem:** Find the electric field and size of the individual depletion layers on either side of a  $pn$  junction for a given diode

• **Given data:** On the  $p$ -type side:  $N_A = 10^{17}/\text{cm}^3$  on the  $n$ -type side:  $N_D = 10^{20}/\text{cm}^3$  from earlier example,  $\phi_j = 0.979 \text{ V}$       $w_{d0} = 0.113 \mu\text{m}$

• **Assumptions:** Room-temperature operation

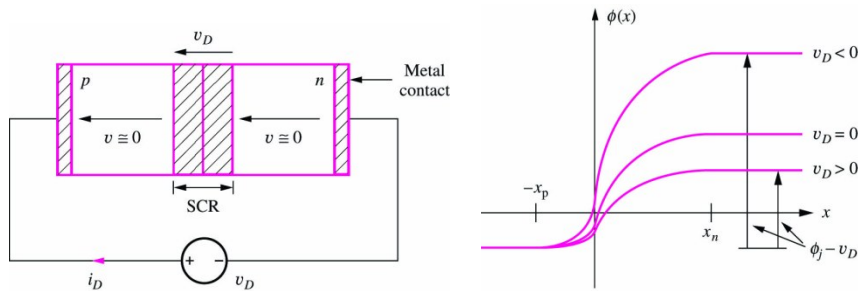
• **Analysis:**

$$w_{d0} = x_n + x_p = x_n \left( 1 + \frac{N_D}{N_A} \right) = x_p \left( 1 + \frac{N_A}{N_D} \right)$$

$$x_n = \frac{w_{d0}}{\left( 1 + \frac{N_D}{N_A} \right)} = 1.13 \times 10^{-4} \mu\text{m} \quad x_p = \frac{w_{d0}}{\left( 1 + \frac{N_A}{N_D} \right)} = 0.113 \mu\text{m}$$

$$E_{MAX} = \frac{2\phi_j}{w_{d0}} = \frac{2(0.979 \text{ V})}{0.113 \mu\text{m}} = 173 \text{ kV/cm}$$

## Diode Junction Potential for Different Applied Voltages



Changes height of potential barrier to diffusion current  
 $\phi_j \rightarrow \phi_j - V$  in all previous formulae

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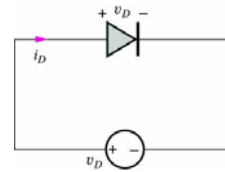
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## Diode Equation

$$i_D = I_S \left[ \exp\left(\frac{qV_D}{nkT}\right) - 1 \right] = I_S \left[ \exp\left(\frac{V_D}{nV_T}\right) - 1 \right]$$

- where
- $I_S$  = reverse saturation current (A)
  - $V_D$  = voltage applied to diode (V)
  - $q$  = electronic charge ( $1.60 \times 10^{-19}$  C)
  - $k$  = Boltzmann's constant ( $1.38 \times 10^{-23}$  J/K)
  - $T$  = absolute temperature
  - $n$  = nonideality factor (dimensionless)
  - $V_T$  =  $kT/q$  = thermal voltage (V) (25 mV at room temp.)



$I_S$  is typically between  $10^{-18}$  and  $10^{-9}$  A, and is strongly temperature dependent due to its dependence on  $n_i^2$ . The nonideality factor is typically close to 1, but approaches 2 for devices with high current densities. It is assumed to be 1 in this text.

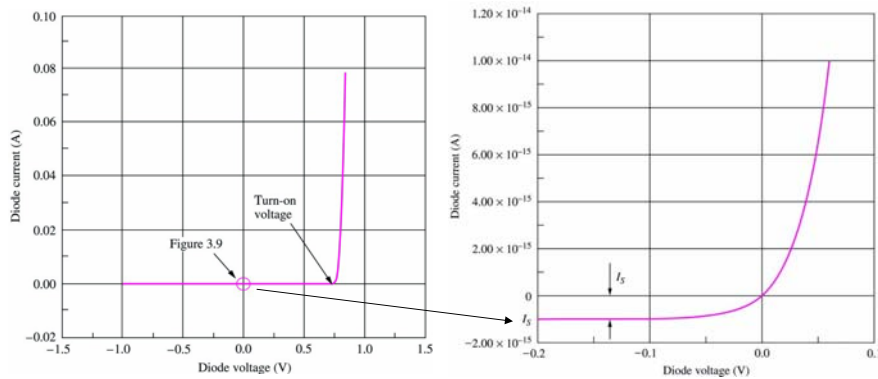
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## Diode $i$ - $v$ Characteristics



The turn-on voltage marks the point of significant current flow.

$I_s$  is called the reverse saturation current.

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## Diode Voltage and Current Calculations (Example)

**Problem:** Find diode voltage for diode with given specifications

**Given data:**  $I_s = 0.1 \text{ fA}$ ,  $I_D = 300 \text{ }\mu\text{A}$

**Assumptions:** Room-temperature dc operation with  $V_T = 0.025 \text{ V}$

**Analysis:**

$$\text{With } I_s = 0.1 \text{ fA} \quad V_D = nV_T \ln\left(1 + \frac{I_D}{I_s}\right) = 1(0.025\text{V}) \ln\left(1 + \frac{3 \times 10^{-4} \text{ A}}{10^{-16} \text{ A}}\right) = 0.718 \text{ V}$$

$$\text{With } I_s = 10 \text{ fA} \quad V_D = 0.603 \text{ V}$$

$$\text{With } I_D = 1 \text{ mA}, I_s = 0.1 \text{ fA} \quad V_D = 0.748 \text{ V}$$

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## Diode Current for Reverse, Zero, and Forward Bias

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- Reverse bias: 
$$i_D = I_S \left[ \exp\left(\frac{v_D}{nV_T}\right) - 1 \right] \cong I_S [0 - 1] \cong -I_S$$
- Zero bias: 
$$i_D = I_S \left[ \exp\left(\frac{v_D}{nV_T}\right) - 1 \right] \cong I_S [1 - 1] \cong 0$$
- Forward bias: 
$$i_D = I_S \left[ \exp\left(\frac{v_D}{nV_T}\right) - 1 \right] \cong I_S \exp\left(\frac{v_D}{nV_T}\right)$$

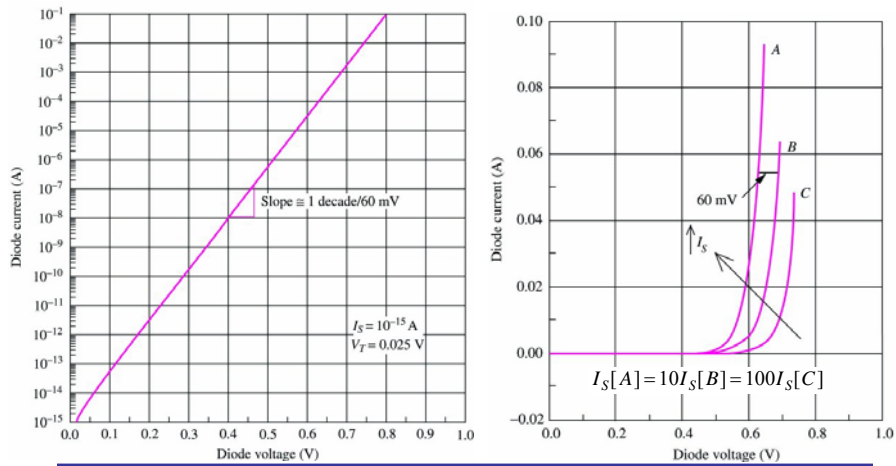
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## Semi-log Plot of Forward Diode Current and Current for Three Different Values of $I_S$

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## Diode Temperature Coefficient

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Diode voltage under forward bias:

$$v_D = V_T \ln\left(\frac{i_D}{I_S} + 1\right) = \frac{kT}{q} \ln\left(\frac{i_D}{I_S} + 1\right) \cong \frac{kT}{q} \ln\left(\frac{i_D}{I_S}\right)$$

Taking the derivative with respect to temperature yields

$$\frac{dv_D}{dT} = \frac{k}{q} \ln\left(\frac{i_D}{I_S}\right) - \frac{kT}{q} \frac{1}{I_S} \frac{dI_S}{dT} = \frac{v_D}{T} - V_T \frac{1}{I_S} \frac{dI_S}{dT} = \frac{v_D - V_{GO} - 3V_T}{T} \quad \text{V/K}$$

Assuming  $i_D \gg I_S$ ,  $I_S \propto n_i^2$ , and  $V_{GO}$  is the silicon bandgap energy at 0K. For a typical silicon diode

$$\frac{dv_D}{dT} = \frac{(0.65 - 1.12 - 0.075)V}{300K} = -1.82 \text{ mV/K} \approx \mathbf{-1.8 \text{ mV}^\circ\text{C}}$$

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End of Lecture 4